



#### 20V N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
	22mΩ @ V <sub>GS</sub> = 4.5V	7.9A
20V	26mΩ @ V <sub>GS</sub> = 2.5V	7.2A
	36mΩ @ V <sub>GS</sub> = 1.8V	6.1A
	50mΩ @ V <sub>GS</sub> = 1.5V	5.2A

### **Description**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- Battery Management Application
- Power Management Functions
- DC-DC Converters

### **Features**

- 0.6mm profile ideal for low profile applications
- PCB footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

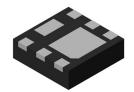
### **Mechanical Data**

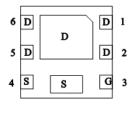
- Case: U-DFN2020-6 TYPE F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (approximate)

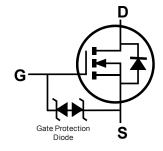
#### U-DFN2020-6 TYPE F











Top View

**Bottom View** 

Pin Out Bottom View

Internal Schematic

### Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Quantity per reel
DMN2022UFDF-7	NC	7	3,000
DMN2022UFDF-13	NC	13	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



NC = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	201	1	2012		2013	20	14	2015		2016	2	2017
Code	Y		Z		Α	Е	3	С		D		Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±8	V		
Continuous Drain Current (Note C) / 4 EV	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	7.9 6.3	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	t<5s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	9.4 7.5	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	40	Α		
Continuous Source-Drain Diode Current	I <sub>S</sub>	2	Α		
Avalanche Current (Note 7) L = 0.1mH	I <sub>AS</sub>	12	Α		
Avalanche Energy (Note 7) L = 0.1mH	E <sub>AS</sub>	8	mJ		

### **Thermal Characteristics**

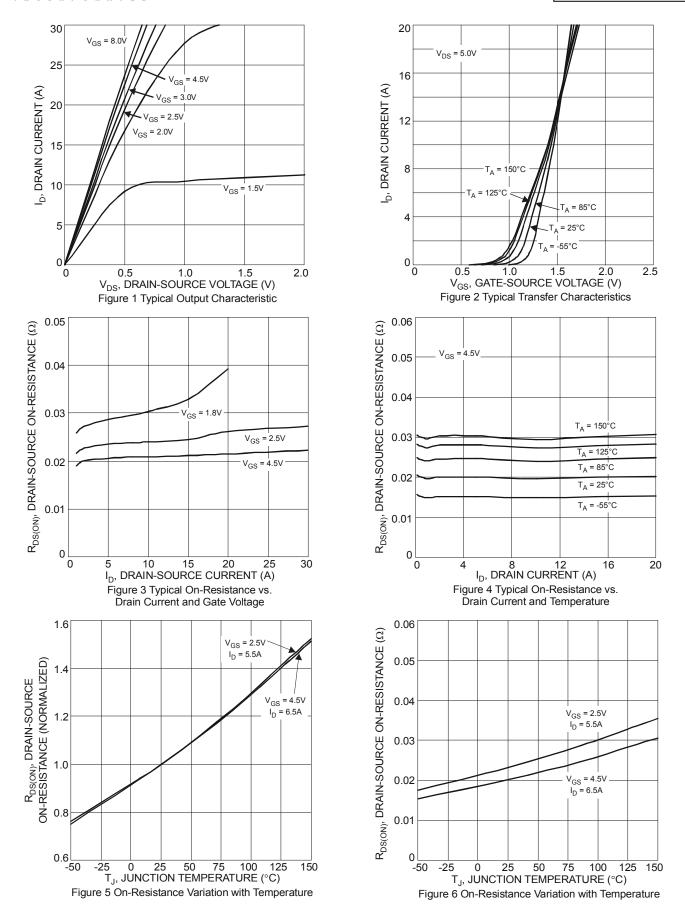
Characteristic		Symbol	Value	Units	
Total Bower Dissination (Note 5)	T <sub>A</sub> = +25°C	C	0.66	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	$P_{D}$	0.42		
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	D	188	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<5s	$R_{\theta JA}$	135	C/VV	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	Б	2.03	W	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +70°C	$P_{D}$	1.31		
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	60	°C/W	
memai Resistance, Junction to Ambient (Note 6)	t<5s	$R_{\theta JA}$	43		
Thermal Resistance, Junction to Case (Note 6)	Steady state	$R_{ heta JC}$	8.3		
Operating and Storage Temperature Range		$T_{J}$ , $T_{STG}$	-55 to +150	°C	

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 8)								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20		_	V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>		I	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$		
Gate-Source Leakage	I <sub>GSS</sub>		l	±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 8)	ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	_	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$		
			15	22		$V_{GS} = 4.5V, I_D = 4A$		
Static Drain-Source On-Resistance	Dec (a)		18	26	mΩ	$V_{GS} = 2.5V, I_D = 4A$		
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	_	24	36	11177	$V_{GS} = 1.8V, I_D = 4A$		
			35	50		$V_{GS} = 1.5V, I_D = 4A$		
Forward Transfer Admittance	Y <sub>fs</sub>	_	18	_	S	$V_{DS} = 5V, I_{D} = 12A$		
Diode Forward Voltage	$V_{SD}$	_	0.7	1.0	V	$V_{GS} = 0V$ , $I_S = 5A$		
DYNAMIC CHARACTERISTICS (Note 9)								
Input Capacitance	C <sub>iss</sub>	_	907	_	pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1.0MHz		
Output Capacitance	Coss	_	98	_				
Reverse Transfer Capacitance	C <sub>rss</sub>		38	_		1 - 1.000112		
Gate Resistance	$R_g$	_	194	_	Ω	$V_{DS}$ = 0V, $V_{GS}$ = 0V, f = 1MHz		
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg		9.8	_				
Total Gate Charge (V <sub>GS</sub> = 8V)	Qg	_	18	_	nC	V <sub>DS</sub> = 10V. I <sub>D</sub> = 6.5A		
Gate-Source Charge	$Q_{gs}$	_	1.5	_	IIC	V <sub>DS</sub> = 10V, I <sub>D</sub> = 6.5A		
Gate-Drain Charge	$Q_{gd}$	_	1.8	_				
Turn-On Delay Time	t <sub>D(on)</sub>	_	56	_				
Turn-On Rise Time	t <sub>r</sub>	_	87	_		$V_{DS} = 10V, V_{GS} = 4.5V,$		
Turn-Off Delay Time	t <sub>D(off)</sub>	_	632	_	ns	$R_G = 6\Omega$ , $R_L = 10\Omega$ , $I_D = 1A$		
Turn-Off Fall Time	t <sub>f</sub>	_	239	_				
Reverse Recovery Time	t <sub>rr</sub>	_	143	_	ns	I <sub>F</sub> = 4A, di/dt = 100A/μs		
Reverse Recovery Charge	Q <sub>rr</sub>		136	_	nC	I <sub>F</sub> = 4A, di/dt = 100A/μs		

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. I<sub>AS</sub> and E<sub>AS</sub> rating are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing.









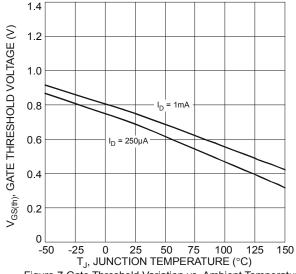
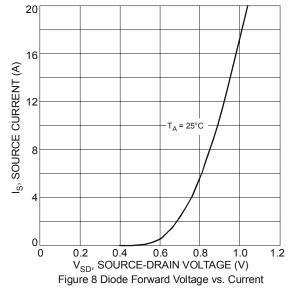
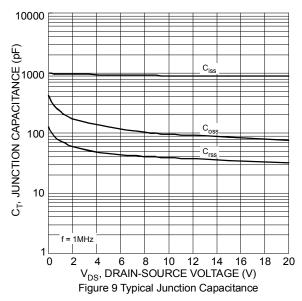
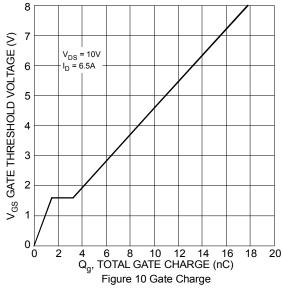
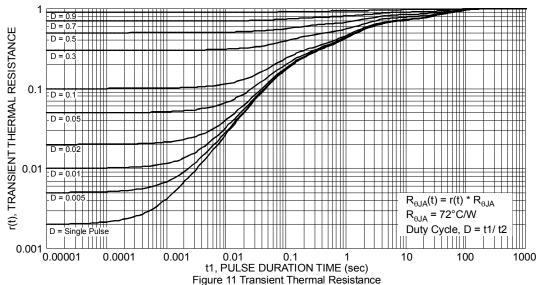


Figure 7 Gate Threshold Variation vs. Ambient Temperature





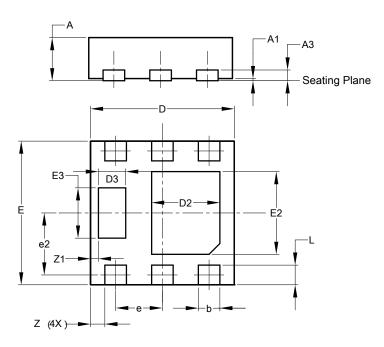






## **Package Outline Dimensions**

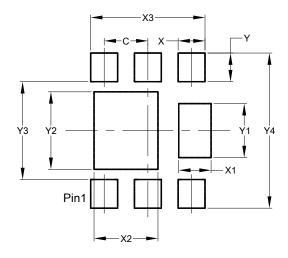
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



U-DFN2020-6						
Dim	Min	Тур				
Α	0.57	0.63	0.60			
A1	0	0.05	0.03			
A3	-	1	0.15			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	0.85	1.05	0.95			
D3	0.33	0.43	0.38			
е		0.65 B	SC			
e2	C	).863 B	SC			
Е	1.95	2.05	2.00			
E2	1.05	1.25	1.15			
E3	0.65	0.75	0.70			
١	0.225	0.325	0.275			
Z	0.20 BSC					
<b>Z</b> 1	0.110 BSC					
All	All Dimensions in mm					

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	0.650		
Х	0.400		
X1	0.480		
X2	0.950		
Х3	1.700		
Υ	0.425		
Y1	0.800		
Y2	1.150		
Y3	1.450		
Y4	2.300		



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